



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Trammel, et al.

Serial No. : 09/940,567

Examiner: Vockrodt, J.

Filed : 8/27/01

Group Art Unit: 2822

For : A PLANAR LIGHTWAVE CIRCUIT ACTIVE DEVICE
METALLIZATION PROCESS

RESPONSE TO OFFICE ACTION

Assistant Commissioner for Patents & Trademarks
Washington, D.C. 20231

Sir:

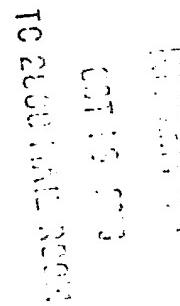
In response to the Office Action mailed on 4/3/03, please consider the following
remarks:

IN THE CLAIMS

Please amend the claims as follows:

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1. (Currently Amended) A method for making a resistive heater for a planar lightwave circuit, the method comprising the steps of:
- a) depositing a resistive layer on a top clad of a planar lightwave circuit;
- b) depositing an interconnect layer onto the resistive layer, wherein the resistive layer comprises tungsten and the interconnect layer comprises aluminum;
- c) etching the interconnect layer to define a heater interconnect, wherein the heater interconnect is disposed over the resistive layer and has a first width;

7/18 Andt 10-21-03
R.Waller
Extenu 10-5-03



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